

D1

12. The device of claim [11] 40 wherein a drive circuit is provided on the second substrate at a region opposed to the [drive] driver circuit [region].

13. The device of claim [11] 40 wherein said [display region] active matrix circuit comprises an amorphous silicon transistor, and said [drive] driver circuit [region] comprises a crystalline silicon transistor.

14. The device of claim [11] 40 wherein said [display region] active matrix circuit comprises a MIM diode.

15. The device of claim [11] 40 wherein said resin material comprises a material selected from the group consisting of an epoxy resin and an ultraviolet hardening resin.

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Contd

17. The device of claim [16] 41 wherein a drive circuit is provided on the second substrate at a region opposed to the [drive] driver circuit [region].

18. The device of claim [16] 41 wherein said [display region] active matrix circuit comprises an amorphous silicon transistor, and said [drive] driver circuit [region] comprises a crystalline silicon transistor.

19. The device of claim [16] 41 wherein said [display region] active matrix circuit comprises a MIM diode.

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Concl

20. The device of claim [16] 41 wherein said resin material comprises a material selected from the group consisting of an epoxy resin and an ultraviolet hardening resin.

21. (amended) The device of claim [6] 40 wherein said sealing [agent] member contains spacers.

22. (amended) The device of claim [16] 41 wherein said sealing [agent] member contains spacers.

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D3

24. (amended) The device of claim [23] 42 wherein said sealing [agent] member contains spacers.

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Please add new claims 25-42 as follows:

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Contd

Sub E1

--25. An electro-optical device comprising:  
a first substrate;  
an active matrix circuit having a plurality of pixels arranged in a matrix form on said first substrate;  
at least on driver circuit for driving said active matrix circuit on said first substrate, each of said active matrix circuit and said driver circuit comprising thin film transistors provided on said first substrate;  
a second substrate opposed to said first substrate;  
a liquid crystal provided between said first substrate and said second substrate; and

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contd

a sealing member provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing member enclosing said active matrix circuit and said driver circuit,

wherein said second substrate has at least one side edge which is substantially aligned with a side edge of said first substrate.

Sub H27

26. The device of claim 25 wherein the thin film transistors of each of said active matrix circuit and said driver circuit are formed on said first substrate through a common process.

27. The device of claim 25 wherein said sealing member overlaps at least a part of said driver circuit.

Sub H37

28. The device of claim 25 wherein the same material as said sealing member is provided on at least said driver circuit.

29. The device of claim 25 wherein said sealing member comprises an ultraviolet-curable resin.

Sub E27

30. An electro-optical device comprising:  
a first substrate;  
an active matrix circuit having a plurality of pixels arranged in a matrix form on said first substrate;  
at least one driver circuit for driving said active matrix circuit on said first substrate, each of said active matrix circuit and said driver circuit comprising thin film transistors provided on said first substrate;  
a second substrate opposed to said first substrate;

a liquid crystal provided between said first substrate and said second substrate; and

a sealing member provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing member enclosing said active matrix circuit and said driver circuit,

wherein said second substrate has at least one side edge which is substantially aligned with a side edge of said first substrate, and

wherein an outer edge of said sealing member is located inside side edges of said first and second substrates.

*D4*  
*contd*

*Sub H57* 31. ~~The device of claim 30 wherein the thin film transistors of each of said active matrix circuit and said driver circuit are formed on said second substrate through a common process.~~

32. The device of claim 30 wherein said sealing member overlaps at least a part of said driver circuit.

*Sub H6* 33. ~~The device of claim 30 wherein the same material as said sealing member is provided on at least said driver circuit.~~

34. The device of claim 30 wherein said sealing member comprises an ultraviolet-curable resin.

*Sub E37* 35. An electro-optical device comprising:  
a first substrate;  
an active matrix circuit having a plurality of pixels arranged in a matrix form on said first substrate;

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at least on driver circuit for driving said active matrix circuit on said first substrate, each of said active matrix circuit and said driver circuit comprising thin film transistors provided on said first substrate;

a second substrate opposed to said first substrate;

a liquid crystal provided between said first substrate and said second substrate;

a sealing member provided between said first substrate and said second substrate for sealing said liquid crystal therebetween, said sealing member enclosing said active matrix circuit and said driver circuit,

wherein said second substrate has at least one side edge which is substantially aligned with a side edge of said first substrate and an outer edge of said sealing member.

Sub  
K1

36. The device of claim 35 wherein said thin film transistor of each of said active matrix elements and said driver circuit is formed through a common process.

37. The device of claim 35 wherein said sealing member overlaps at least a part of said driver circuit.

Sub H8

38. The device of claim 35 wherein the same material as said sealing member is provided on at least said driver circuit.

39. The device of claim 35 wherein said sealing member comprises an ultraviolet-curable resin.

Sub  
F4

40. An electro-optical device comprising:

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contd

a first substrate;  
an active matrix circuit having a plurality of pixels arranged in a matrix form on said first substrate;  
at least one driver circuit for driving said active matrix circuit on said first substrate, each of said active matrix circuit and said driver circuit comprising thin film transistors provided on said first substrate;  
a second substrate opposed to said first substrate;  
a liquid crystal provided between said first substrate and said second substrate;  
a resin material provided between said first and second substrates, said resin material contacting with said second substrate and covering said driver circuit; and  
a sealing member provided between said first substrate and said second substrate and enclosing said active matrix elements and said driver circuit.

41. An electro-optical device comprising:

a first substrate;  
an active matrix circuit having a plurality of pixels arranged in a matrix form on said first substrate;  
at least one driver circuit for driving said active matrix circuit on said first substrate, each of said active matrix circuit and said driver circuit comprising thin film transistors provided on said first substrate;  
a second substrate opposed to said first substrate;  
a liquid crystal provided between said first substrate and said second substrate;

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a resin material provided between said first and second substrates, said resin material contacting with said second substrate and covering said driver circuit; and

a sealing member provided between said first substrate and said second substrate and enclosing said driver circuit.

42. An electro-optical device comprising:

a first substrate;

an active matrix circuit having a plurality of pixels arranged in a matrix form on said first substrate;

at least on driver circuit for driving said active matrix circuit on said first substrate, each of said active matrix circuit and said driver circuit comprising thin film transistors provided on said first substrate;

a second substrate opposed to said first substrate;

a liquid crystal provided between said first substrate and said second substrate;

a resin material provided between said first and second substrates, said resin material contacting with said second substrate and covering said driver circuit;

a sealing member provided between said first substrate and said second substrate and enclosing said active matrix elements and said driver circuit;

a first inlet provided for introducing said sealing member and said liquid crystal between said first substrate and said second substrate; and

a second inlet provided for introducing said sealing member and said resin material between said first substrate and said second substrate.--

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